

AMENDMENT TO THE SPECIFICATION

Please amend specification paragraph [0053] as indicated below:

--[0053] FIG. 14 shows chart 330 depicting comparative power dissipation benchmarks from ~~layout 300-A and B~~ package 2 (FIG. 1) and package 301 (FIG. 11). The power dissipation benchmark results for solder ball package 2 are represented by “CSP” line 331 and the results for solder bar package 301 are represented “Bars” line 332. Solder bar package 301 produced a 550mW savings at 25A and 2A more current at 2W dissipation over solder ball package 2.--